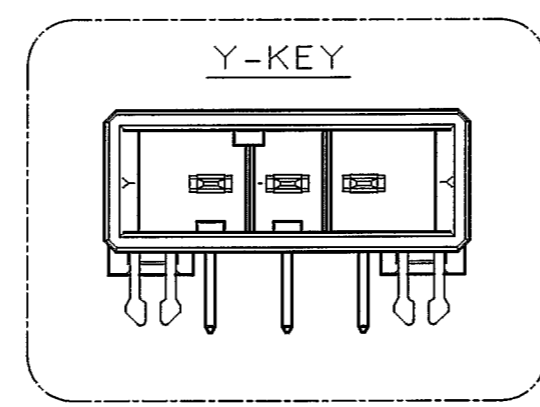
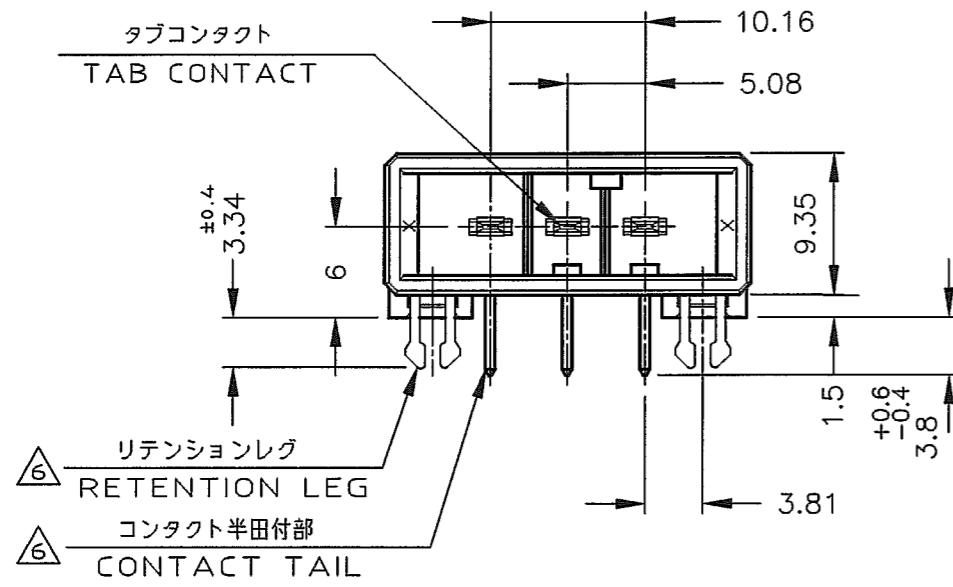
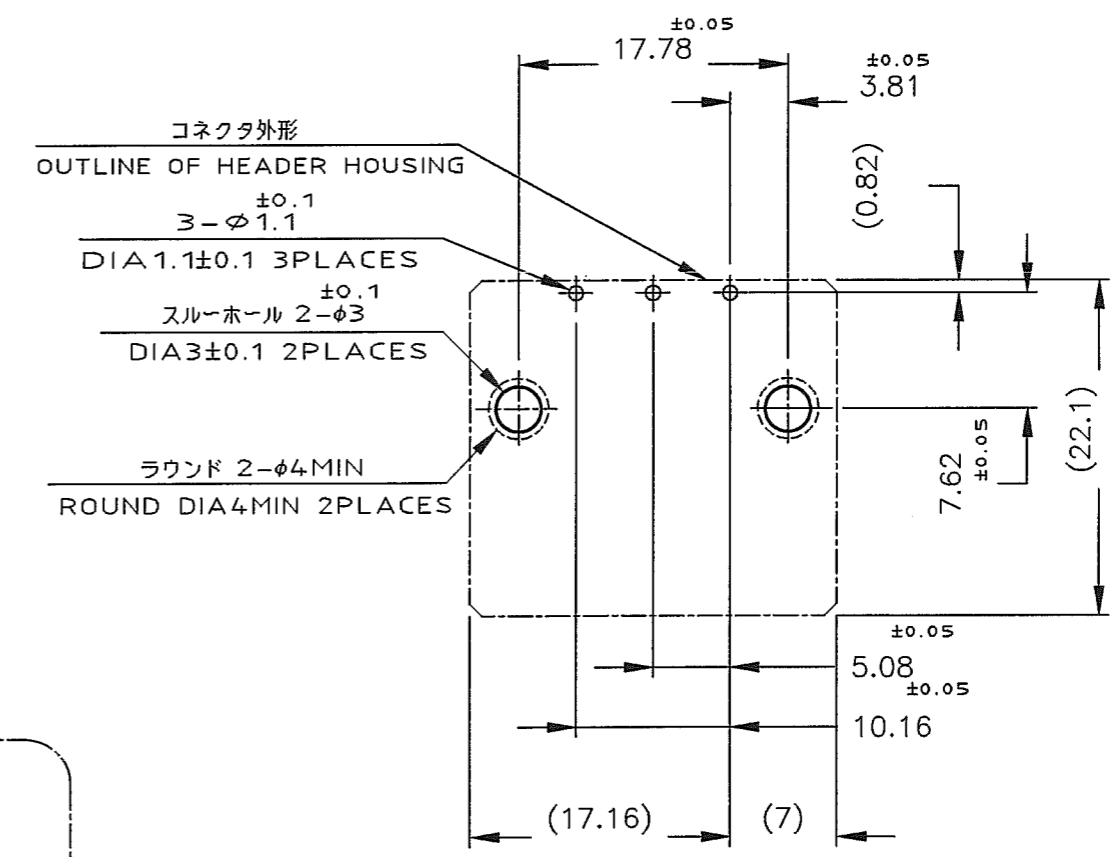
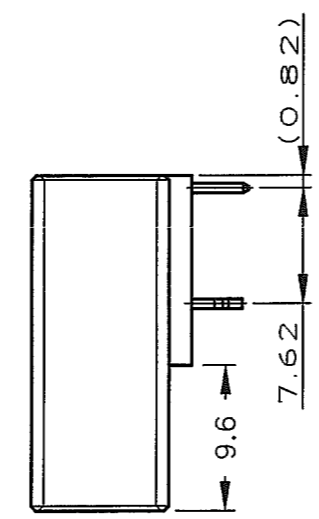
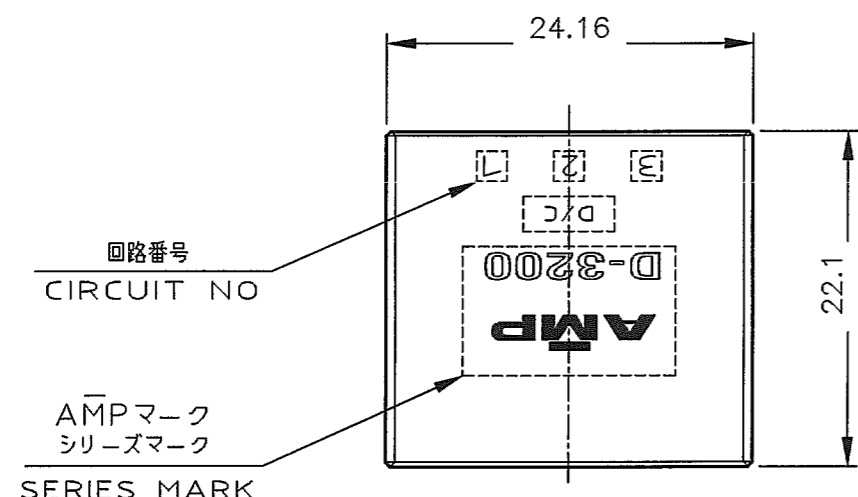


NUMBER 178138
 3rd ANGLE PROJECTION
 METRIC
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
 PRINT DIST
 AMP-J REV.10/'83



推奨基板取付け穴寸法
 PC 基板厚: 1.6 ± 0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6 ± 0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)

- NOTES
- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
 - FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
 - FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
 - FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
 - FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
 - FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

- 注記
- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
 コンタクト: 銅合金
 リテンションレグ: 銅合金
 - めっき: コンタクト: 全面Ni下地
 接触部: 0.38 μm MIN金めっき
 - めっき: コンタクト: 全面Ni下地
 接触部: 0.76 μm MIN金めっき
 - めっき: コンタクト: 全面Ni下地
 接触部: 2.0 μm MINスズめっき
 - めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の上に半田めっき
 - めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の上にスズめっき

△6	△4	2-178138-5	Y
△6	△3	2-178138-3	Y
△6	△2	2-178138-2	Y
△6	△4	1-178138-5	X
△6	△3	1-178138-3	X
△6	△2	1-178138-2	X
(FINISH)		製品番号 (PART NO.)	KEY

E	REVISED (FJD0-0039-03)	T.S.M.	4/23
D	REVISED (FJD0-0114-03)	T.S.M.	25/APR/03
C	REVISED (FJ00-1335-97)	K.I.H.	5/SEP/97
B	REVISED (FJ00-5532-96)	K.I.Y.	7/JAN/97
A	REDRAWN (FJ00-2183-95)	K.I.S.M.	3-23/95
LTR	REVISION RECORD	DR	CHK DATE

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tyco Electronics Tyco Electronics AMP K.K. Kawasaki, Japan

WIRE RANGE	INSULATION DIA	NAME
mm ² (AWG -)	mmφ	3 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200
MATERIAL	FINISH	一般公差 (GENERAL TOLERANCE)
SEE NOTE 注記参照	SEE NOTE 注記参照	10MF : ±0.3
DR. 20/MAR/95 K.IKEDA	DE. 20/MAR/95 K.IKEDA	1000R 30MT : ±0.4
CHK. 23/MAR/95 S.MANABE	APP. 23/MAR/95 S.MANABE	300R1000T : ±0.5
		角 度 : ±3'

SIZE	LOC	NUMBER
A3	J	C-178138
SCALE	REV.	SHEET
2-1	E	1 OF 1